IEEE P802.11  
Wireless LANs

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| IEEE 802.11bf Teleconference Meeting Minutes: September and October 2020 | | | | |
| Date: 2020-10-29 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
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Abstract

This document contains the meeting minutes of IEEE 802.11bf teleconferences held in September and October 2020.

**Teleconference on September 29th, 2020**

1. The IEEE 802.11 TGbf teleconference was called to order at 10:00am ET by the Chair (Tony Xiao Han, Huawei).
   1. Attendance log can be found in Appendix 1.
2. The agenda for the meeting can be found in IEEE 802.11-20/1547r0.
3. Guidelines on “Meeting Protocol, Attendance, Voting & Document Status” (slide 4) were reviewed. No items noted.
4. Patent policy guidelines (slides 6-9) were reviewed. No items noted.
5. Guidelines on the IEEE Codes of Ethics & Conduct, "individual process," and "fair & equitable consideration" (slides 10-12) were reviewed. Required notices (slide 13) were also reviewed. No items noted.
6. The proposed agenda (slide 14) was reviewed and approved without objection.
7. Group goals for the next meetings, such as technical presentations/discussions, were discussed (slide 15). No items noted.
8. Chair reviewed the call for contributions (slide 16) and future teleconference times (slide 17) slides.
9. Presentation of “WLAN Sensing Procedures and Use Cases,” doc. IEEE 11-20/1266r0, by Claudio da Silva (Intel).
   1. Presenter reviewed the presentation given to SENS SG in the Septermber 1st teleconference, and opened floor for discussion. Technical discussion followed.
   2. The SP found in slide 17 of 11-20/1266r0 was conducted and resulted in: Yes 32/No 1/Abstain 2.
10. Presentation of “Discussion on WLAN sensing sequence design - follow up,” doc. IEEE 11-20/1529r0, by Rui Du (Huawei).
    1. Presentation focused on the impact of two different types of receivers (correlation, matched filter) to R-D map/ambiguity functions. Floor was opened for Q&A and technical discussion followed.
11. Presentation of “Collaborative WLAN sensing,” doc. IEEE 11-20/1533r0, by Sang Kim (LG).
    1. Presenter went over all the material/slides found in 11-20/1533r0. Due to lack of time, Q&A was deferred to the next TGbf teleconference.
12. Chair discussed potential changes to the teleconference times found in slide 17. Changes will be reflected in 11-20/1547r1.
13. Meeting adjourned at 11:40am ET.

**Teleconference on October 13, 2020**

1. The IEEE 802.11 SENS SG teleconference was called to order at 10:04am ET by the Chair (Tony Xiao Han, Huawei).
   1. Attendance log can be found in Appendix 2.

2. The agenda for the meeting can be found in IEEE 802.11-20/1621r0.

3. Guidelines on “Meeting Protocol, Attendance, Voting & Document Status” (slide 4) were reviewed. No items noted.

4. Patent policy guidelines (slides 6-9) were reviewed. No items noted.

5. Guidelines on the IEEE Codes of Ethics & Conduct, "individual process," and "fair & equitable consideration" (slides 10-12) were reviewed. Required notices (slide 13) were also reviewed. No items noted.

6. The proposed agenda (slide 14) was reviewed and approved without objection.

1. Chair reviewed the call for contributions (slide 15) and future teleconference times (slide 16) slides.
   1. Starting times of the November 17 and December 1 teleconferences was adjusted (from 10am to 9am ET) to reflect the end of daylight savings time.

8. Discussion of the presentation “Collaborative WLAN sensing,” doc. IEEE 11-20/1533r0, presented in the September 29th teleconference, by Sang Kim (LG).

* 1. Presenter quickly went over the slides found in 11-20/1533r0.
  2. Technical discussion on different aspects of the proposal, such as its relation to the P2P feature currently being defined in 11be and its expected overhead.

1. Presentation of “WLAN sensing usage model: Sneeze sensing” by Rui Du (Huawei), Doc. IEEE 11-20/1640r0.
2. Presentation was followed by Q&A. Question on the definition of resolution and accurancy shown in slide 6.
3. Presentation of “WLAN sensing link level simulation” by Rui Du (Huawei), Doc. IEEE 11-20/1642r0.
4. Presentation was followed by Q&A. Technical discussion around the use of theoretical tools (such as ambiguity function) instead of LLS, performance parameters to be considered, bands of interest, and channel models.
5. Meeting adjourned at 11:25am ET.

**Appendix 1: Attendance log for the September 29th, 2020 teleconference**

The list below was recorded from IMAT and may be incomplete.

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| Aboulmagd, Osama | Huawei Technologies Co. Ltd |
| Agrawal, Sandeep | C-DOT/Centre for Development of Telematics |
| Aldana, Carlos | Facebook |
| Au, Kwok Shum | Huawei Technologies Co.,  Ltd |
| Au, Oscar | Origin Wireless |
| Aygul, Mehmet | Istanbul Medipol University; Vestel |
| Beg, Chris | Cognitive Systems Corp. |
| Berger, Christian | NXP Semiconductors |
| Carney, William | Sony Corporation |
| Chen, Cheng | Intel Corporation |
| Choi, Jinsoo | LG ELECTRONICS |
| da Silva, Claudio | Intel Corporation |
| Dong, Xiandong | Xiaomi Inc. |
| Du, Rui | Huawei Technologies Co., Ltd |
| HAN, Xiao | Huawei Technologies Co. Ltd |
| Handte, Thomas | Sony Corporation |
| Haskou, Abdullah | InterDigital, Inc. |
| Hong, Hanseul | Yonsei University |
| Jang, Insun | LG ELECTRONICS |
| Kasher, Assaf | Qualcomm Incorporated |
| Kim, Sang Gook | LG ELECTRONICS |
| Lim, Dong Guk | LG ELECTRONICS |
| Lopez, Miguel | Ericsson AB |
| PESIN, ANTHONY | InterDigital, Inc. |
| Pushkarna, Rajat | Panasonic Asia Pacific Pte Ltd. |
| Rafique, Saira | Istanbul Medipol University, Vestel |
| Raissinia, Alireza | Qualcomm Incorporated |
| Rantala, Enrico-Henrik | Nokia |
| RISON, Mark | Samsung Cambridge Solution Centre |
| Sand, Stephan | German Aerospace Center (DLR) |
| Sedin, Jonas | Ericsson AB |
| Solaija, Muhammad Sohaib | Istanbul Medipol University; Vestel |
| Sosack, Robert | Molex Incorporated |
| Sun, Yingxiang | Huawei Technologies Co. Ltd |
| Tan, Danny | Huawei Technologies Co.,  Ltd |
| Tsai, Tsung-Han | MediaTek Inc. |
| Turkmen, Halise | Vestel |
| Varshney, Prabodh | Nokia |
| Wang, Chao Chun | MediaTek Inc. |
| Wang, Pu | Mitsubishi Electric Research Labs (MERL) |
| YANG, RUI | InterDigital, Inc. |
| Zhang, Meihong | Huawei Technologies Co., Ltd |

**Appendix 2: Attendance log for the October 13, 2020 teleconference**

The list below was recorded from IMAT and may be incomplete.

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| --- | --- |
| Agrawal, Sandeep | C-DOT/Centre for Development of Telematics |
| Aldana, Carlos | Facebook |
| Al Falujah, Iyad | ON Semiconductor |
| Allegue Martinez, Michel | Aerial Technologies Inc |
| Ansley, Carol | IEEE member / Self Employed |
| Anwyl, Gary | MediaTek Inc. |
| Au, Oscar | Origin Wireless |
| Aygul, Mehmet | Istanbul Medipol University; Vestel |
| Beg, Chris | Cognitive Systems Corp. |
| Berger, Christian | NXP Semiconductors |
| Chen, Cheng | Intel Corporation |
| Chen, Na | MaxLinear Corp |
| Cheng, Gang | Nokia |
| Choi, Jinsoo | LG ELECTRONICS |
| Costa, D.Nelson | Peraso Technologies Incorporated |
| da Silva, Claudio | Intel Corporation |
| Dong, Xiandong | Xiaomi Inc. |
| Du, Rui | Huawei Technologies Co., Ltd |
| Dwyer, Johanna | IEEE member / Self Employed |
| HAN, Xiao | Huawei Technologies Co. Ltd |
| Haskou, Abdullah | InterDigital, Inc. |
| Kasher, Assaf | Qualcomm Incorporated |
| Kim, Sang Gook | LG ELECTRONICS |
| Kwon, Young Hoon | NXP Semiconductors |
| Levitsky, Ilya | IITP RAS |
| Lim, Dong Guk | LG ELECTRONICS |
| Lindskog, Erik | SAMSUNG |
| Ma, Li | MediaTek Inc. |
| Martinez Vazquez, Marcos | MaxLinear Corp |
| Ozbakis, Basak | VESTEL Electronics Corp. |
| Pushkarna, Rajat | Panasonic Asia Pacific Pte Ltd. |
| Rafique, Saira | Istanbul Medipol University, Vestel |
| Raissinia, Alireza | Qualcomm Incorporated |
| Rantala, Enrico-Henrik | Nokia |
| Sun, Yingxiang | Huawei Technologies Co. Ltd |
| Tsai, Tsung-Han | MediaTek Inc. |
| Wang, Chao Chun | MediaTek Inc. |
| Wang, Pu | Mitsubishi Electric Research Labs (MERL) |
| Xin, Yan | Huawei Technologies Co. Ltd |
| Yee, James | MediaTek Inc. |
| Zeng, Ruochen | NXP Semiconductors |
| Zhang, Meihong | Huawei Technologies Co., Ltd |